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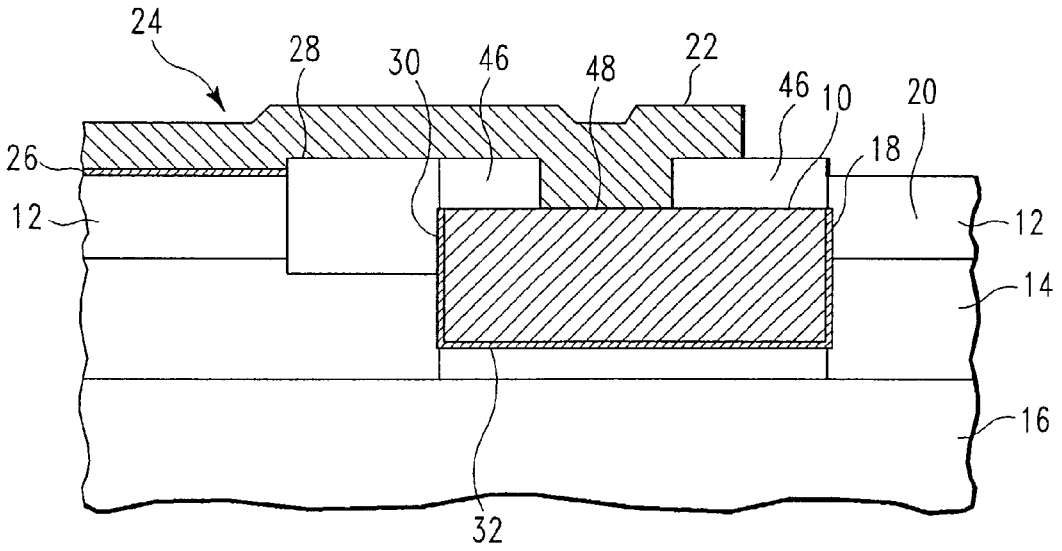
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(54) Title: ENHANCED STRUCTURE AND METHOD FOR BURIED LOCAL INTERCONNECTS



(57) Abstract: A structure and method is disclosed for forming a buried interconnect (10) of an integrated circuit in a single crystal semiconductor layer (12) of a substrate. The buried interconnect is formed of a deposited conductor and has one or more vertical sidewalls (18) which contact a single crystal region of an electronic device (20) formed in the single crystal semiconductor layer.

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